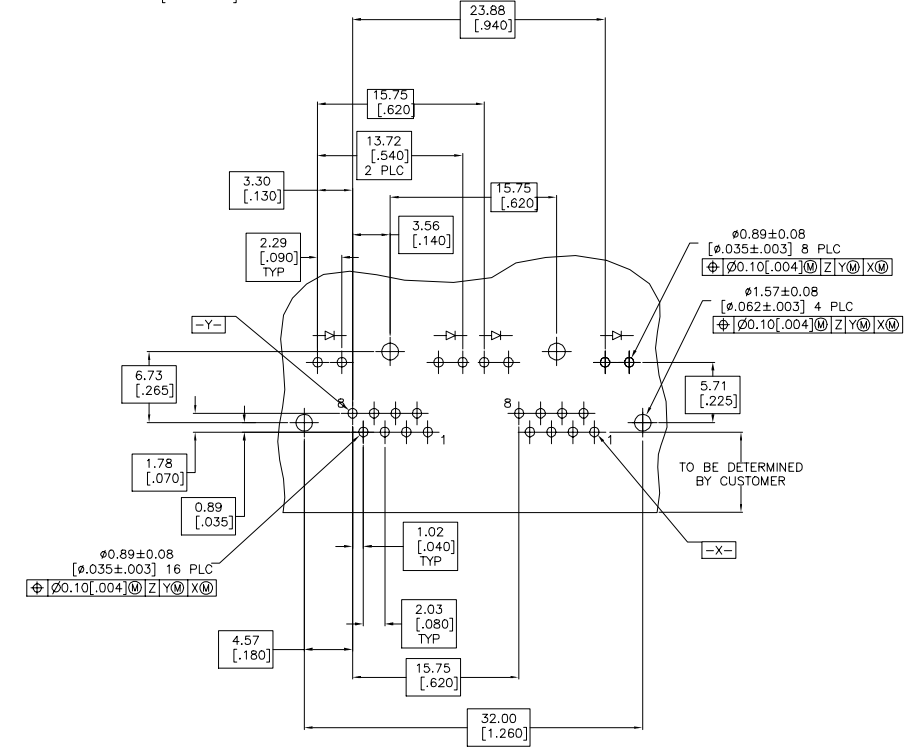
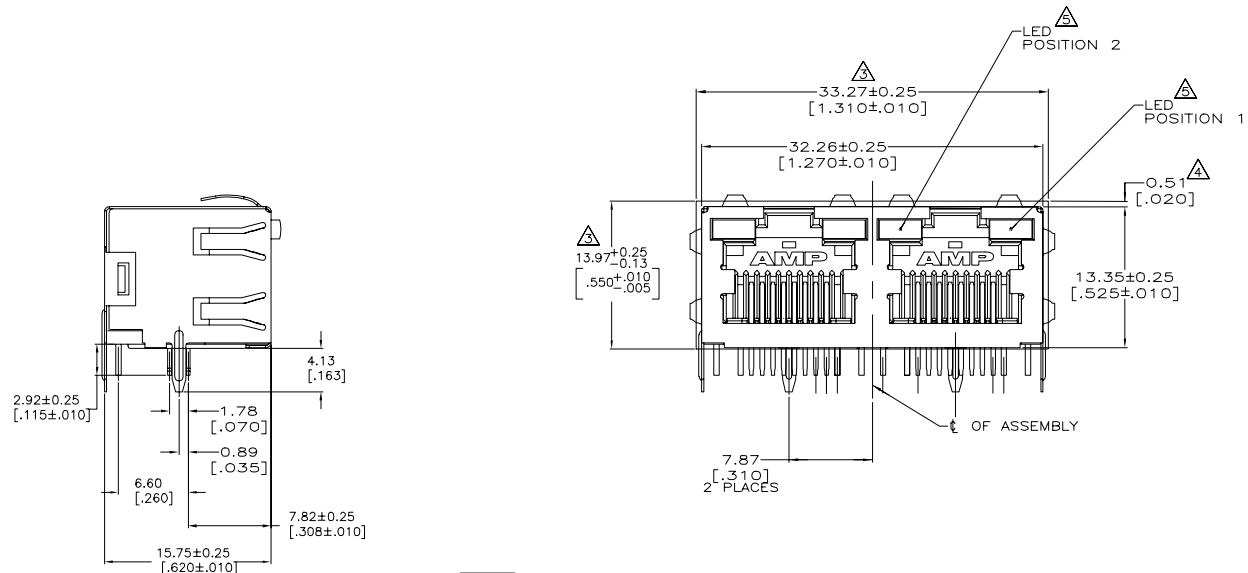


REVISIONS				
REV	DATE	DESCRIPTION	BY	APP'D
C1	ECO-18-014918		27SEP2020	RR SH



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT  
COMPONENT SIDE

- MATERIAL:  
HOUSING - HIGH TEMPERATURE THERMOPLASTIC,  
COLOR: BLACK, UL94V-0  
TERMINALS - 0.36[.014] THICK PHOS BRONZE  
PLATED WITH 3.81µm[.000150] MIN THICK  
BRIGHT TIN LEAD IN SOLDER AREA, 1.27µm[.000050]  
MIN GOLD IN LOCALIZED PLATE AREA. ENTIRE  
TERMINAL PLATED WITH 1.27µm[.000050] MIN  
THICK NICKEL.  
SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY  
PREPLATED WITH 1.27µm[.000050] MIN SATIN  
NICKEL WITH 2.03µm[.000080] MIN TIN POST  
DIPPED ON PCB GROUND TABS  
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY  
LENS, 0.51 X 0.51[.020 X .020] CARBON STEEL  
WIREFRAME LEADS PLATED WITH 8.89µm[.000350]  
TIN/COPPER OVER 2.03µm[.000080] SILVER OVER  
1.02µm[.000040] NICKEL UNDERPLATE OVER  
2.03µm[.000080] COPPER UNDERPLATE
  - JACK CAVITY CONFORMS TO FCC RULES AND  
REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
  - △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR  
AND TOP PANEL OPENING.
  - △ SEE TABLE FOR COLOR OF LEDS AND NUMBER  
REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT  
IR REFLOW SOLDERING PROCESS COMPATIBLE.

OBSELETE	GREEN	GREEN	1364173-5
OBSELETE	YELLOW	GREEN	1364173-1
	POSITION 2	POSITION 1	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE: 11/11/2019	DESIGNED BY: J. MORRIS	DATE: 11/11/2019	DRWNO: 1364173-4
DIMENSIONS: mm (INCHES)		APPROVED BY: D. DIXON	DATE: 11/11/2019	DRWNO: 1364173-4	REV: 1
OTHER PARTS LISTED:		PRODUCT SPEC: 108-1163-4	APPLICATION SPEC: 114-2154	SIZE: 114-2154	RESTRICTED TO: -
MATERIAL: -		FINISH: -	WEIGHT: 0	SCALE: 1:1	SHEET: 1 OF 1
CUSTOMER DRAWING		DATE CODE: A100779	DRAWING NO: C=1364173	REV: -	REV: C1